

Amendments to the Specification

Please replace paragraph [0068] with the following rewritten paragraph:

-- FIG. 7 is a diagrammatic sketch in a sectional view thru a memory package stack, generally at **70**, in an arrangement suitable for use in various embodiments of the invention as shown for example in FIGS. **8** and **9**. Referring to FIG. 7, the memory package stack **70** includes two LGA type packages **72**, **76**, stacked in the same orientation (both inverted in this illustration) one over the other and separated by spacer **723**. The two stacked LGA packages are mounted onto a common package stack substrate **74**, using an adhesive between the upper surface of the common package stack substrate **74** and the downward-facing surface of the package encapsulation of the lower LGA package **72**. The die in each LGA package is affixed to a die attach surface of its package substrate using an adhesive. Electrical connection of the die in each LGA package is made by way of wire bonds between wire bond pads (not shown) on the active surface of the die and wire bonding sites on the die attach surface of the LGA package substrate, and the wire bonds and the active surface are protected by an encapsulation material. Connection of each memory LGA package to the common memory stack substrate is made by wire bonding (wire bonds **726** for package **76**; wire bonds **722** for package **72**) between wire bond pads on the upper surfaces **721**, **761** of the respective LGA package substrates and wire bond sites (e.g., **73**) on the common package stack substrate **74**. The spacer **723** is arranged between the “upward facing” surface **761** of the lower LGA package **72** substrate and the “downward facing” surface **727** of the encapsulation of the upper LGA package **76**. The space is of sufficient thickness to provide relief between the two packages to accommodate the loops of the wire bonds **722**. --

Please replace paragraph [0071] with the following rewritten paragraph:

As shown in FIG. **8**, a multipackage module, generally at **800**, according to another aspect of the invention can be made by affixing spaced stacked LGA packages **76**, **72**, as described generally with reference to FIG. 7, onto memory attach portions of a module substrate **82** constructed and mounted with a processor generally as shown in FIG. **5B**. In the configuration of FIG. **8**, the module substrate is effectively the common memory stack substrate **74** of FIG. 7, and the z-interconnection between the memory packages in each stack **70** is made by way of wire bonds from the respective LGA package substrates to the upper surface of the module substrate.

As in other embodiments, solder balls **818** are attached in an array to solder ball sites in the lower surface of the module substrate, the assembly is mechanically stabilized by encapsulant material **817**, and connection to apparatus for use, as for example to a motherboard (not shown), is made by solder reflow of the solder balls **818**.